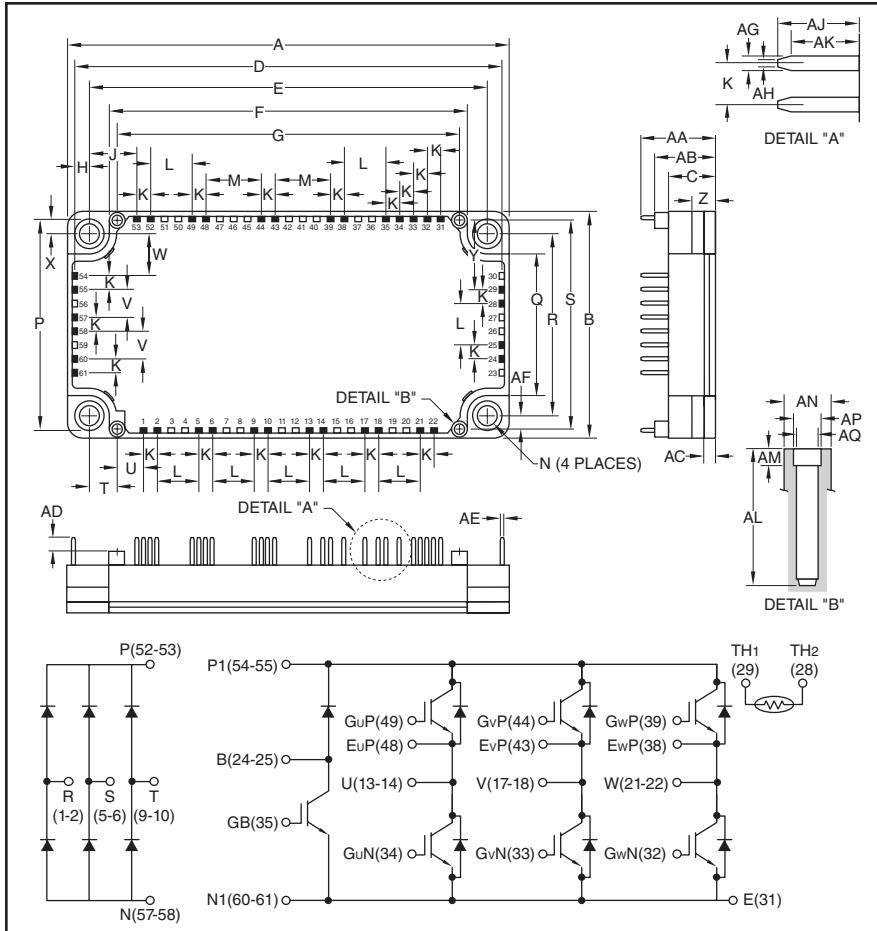
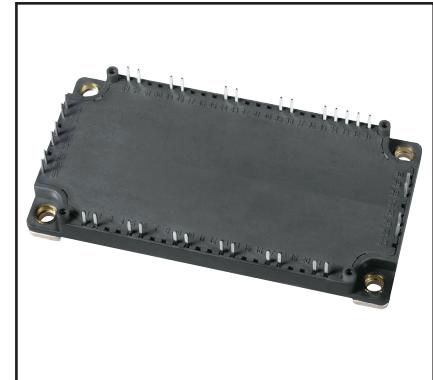


Powerex, Inc., 173 Pavilion Lane, Youngwood, Pennsylvania 15697 (724) 925-7272

NX-Series CIB Module
 (3Ø Converter + 3Ø Inverter + Brake)
35 Amperes/1200 Volts

Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.79	121.7
B	2.44	62.0
C	0.51	13.0
D	4.65	118.1
E	4.33±0.02	110.0±0.5
F	3.89	99.0
G	3.72	94.5
H	0.16	4.06
J	0.51	13.09
K	0.15	3.81
L	0.45	11.43
M	0.6	15.24
N	0.22 Dia.	5.5 Dia.
P	2.30	58.4
Q	1.53	39.0
R	1.97±0.02	50.0±0.5
S	2.26	57.5
T	0.30	7.75
U	0.28	7.25
V	0.3	7.62


Description:

CIBs are low profile and thermally efficient. Each module consists of a three-phase diode converter section, a three-phase inverter section and a brake circuit. A thermistor is included in the package for sensing the baseplate temperature. 5th Generation CSTBT chips yield low loss.

Features:

- Low Drive Power
- Low $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

Applications:

- AC Motor Control
- Motion/Servo Control
- Photovoltaic/Fuel Cell

Ordering Information:

Example: Select the complete module number you desire from the table below -i.e.

CM35MX-24A is a 1200V (V_{CES}), 35 Ampere CIB Power Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	35	24



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Absolute Maximum Ratings, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	CM35MX-24A	Units
Power Device Junction Temperature	T_j	-40 to 150	°C
Storage Temperature	T_{stg}	-40 to 125	°C
Mounting Torque, M5 Mounting Screws	—	31	in-lb
Module Weight (Typical)	—	270	Grams
Baseplate Flatness, On Centerline X, Y (See Below)	—	$\pm 0 \sim +100$	μm
Isolation Voltage, AC 1 minute, 60Hz Sinusoidal	V_{ISO}	2500	Volts

Inverter Sector

Collector-Emitter Voltage (G-E Short)	V_{CES}	1200	Volts
Gate-Emitter Voltage (C-E Short)	V_{GES}	± 20	Volts
Collector Current ($T_C = 105^\circ\text{C}$) ^{*1}	I_C	35	Amperes
Peak Collector Current (Pulse) ^{*3}	I_{CM}	70	Amperes
Emitter Current ($T_C = 25^\circ\text{C}$) ^{*1}	I_E ^{*2}	35	Amperes
Peak Emitter Current (Pulse) ^{*3}	I_{EM} ^{*2}	70	Amperes
Maximum Collector Dissipation ($T_C = 25^\circ\text{C}$) ^{*1*4}	P_C	295	Watts

Brake Sector

Collector-Emitter Voltage (G-E Short)	V_{CES}	1200	Volts
Gate-Emitter Voltage (C-E Short)	V_{GES}	± 20	Volts
Collector Current ($T_C = 121^\circ\text{C}$) ^{*1}	I_C	20	Amperes
Peak Collector Current (Pulse) ^{*3}	I_{CM}	40	Amperes
Maximum Collector Dissipation ($T_C = 25^\circ\text{C}$) ^{*1*4}	P_C	260	Watts
Repetitive Peak Reverse Voltage (Clamp Diode Part)	V_{RRM} ^{*2}	1200	Volts
Forward Current ($T_C = 25^\circ\text{C}$) ^{*1}	I_F ^{*2}	20	Amperes
Forward Current (Pulse) ^{*3}	I_{FM} ^{*2}	40	Amperes

Converter Sector

Repetitive Peak Reverse Voltage	V_{RRM}	1600	Volts
Recommended Input Voltage	E_a	440	Volts RMS
DC Output Current (3-Phase Full Wave Rectifying, $T_C = 141^\circ\text{C}$) ^{*1}	I_O	35	Amperes
Surge Forward Current (sine Half-wave 1 Cycle Peak Value, $F = 60\text{Hz}$, Non-repetitive)	I_{FSM}	350	Amperes
Current Square Time (Value for One Cycle of Surge Current)	I^2t	510	A^2s

^{*1} Case temperature (T_C) and heatsink temperature (T_f) are defined on the surface of the baseplate and heatsink at just under the chip.

^{*2} I_E , I_{EM} , V_{EC} , t_{rr} and Q_{rr} represent ratings and characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

I_F , I_{FM} , I_{RRM} , V_{FM} and V_{RRM} represent ratings and characteristics of the clamp diode.

^{*3} Pulse width and repetition rate should be such that device junction temperature (T_j) does not exceed $T_{j(\max)}$ rating.

^{*4} Junction temperature (T_j) should not increase beyond $T_{j(\max)}$ rating.

CM35MX-24A

NX-Series CIB Module

(3Ø Converter + 3Ø Inverter + Brake)

35 Amperes/1200 Volts

Electrical and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Inverter Sector

Characteristics		Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector Cutoff Current	I_{CES}		$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$		$I_C = 3.5mA, V_{CE} = 10V$	6	7	8	Volts
Gate Leakage Current	I_{GES}		$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	μA
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$		$I_C = 35A, V_{GE} = 15V, T_j = 25^{\circ}C$ *5	—	2.0	2.6	Volts
			$I_C = 35A, V_{GE} = 15V, T_j = 125^{\circ}C$ *5	—	2.2	—	Volts
			$I_C = 35A, V_{GE} = 15V, \text{Chip}$	—	1.9	—	Volts
Input Capacitance	C_{ies}			—	—	6.0	nF
Output Capacitance	C_{oes}		$V_{CE} = 10V, V_{GE} = 0V$	—	—	0.53	nF
Reverse Transfer Capacitance	C_{res}			—	—	0.12	nF
Total Gate Charge	Q_G		$V_{CC} = 600V, I_C = 35A, V_{GE} = 15V$	—	180	—	nC
Inductive Load	Turn-on Delay Time	$t_{d(on)}$		—	—	100	ns
Load	Turn-on Rise Time	t_r	$V_{CC} = 600V, I_C = 35A,$	—	—	50	ns
Switch	Turn-off Delay Time	$t_{d(off)}$	$V_{GE} = \pm 15V,$	—	—	300	ns
Time	Turn-off Fall Time	t_f	$R_G = 9.1\Omega, I_E = 35A,$	—	—	600	ns
Reverse Recovery Time	t_{rr}^{*2}		Inductive Load Switching Operation	—	—	200	ns
Reverse Recovery Charge	Q_{rr}^{*2}			—	1.5	—	μC
Emitter-Collector Voltage	V_{EC}^{*2}		$I_E = 35A, V_{GE} = 0V, T_j = 25^{\circ}C$ *5	—	2.6	3.4	Volts
			$I_E = 35A, V_{GE} = 0V, T_j = 125^{\circ}C$ *5	—	2.16	—	Volts
			$I_E = 35A, V_{GE} = 0V, \text{Chip}$	—	2.5	—	Volts

Thermal and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case**	$R_{th(j-c)Q}$	Per IGBT*1	—	—	0.42	°C/W
Thermal Resistance, Junction to Case**	$R_{th(j-c)D}$	Per FWDI*1	—	—	0.69	°C/W
Contact Thermal Resistance**	$R_{th(c-f)}$	Case to Heatsink (Per 1 Module)	—	0.015	—	°C/W
		Thermal Grease Applied*1*7				
Internal Gate Resistance	R_{Gint}	$T_C = 25^\circ\text{C}$	—	0	—	Ω
External Gate Resistance	R_G		8.9	—	89	Ω

****Thermal resistance values are per 1 element.**

*1 Case temperature (T_C) and heatsink temperature (T_f) are defined on the surface of the baseplate and heatsink at just under the chip.

*² E_F , I_{FM} , V_{FC} , t_{rr} and Q_{rr} represent ratings and characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWD).

$|I_E|$, $|I_{FM}|$, $|V_{EC}|$, $|I_{PP}|$ and $|Q_{PP}|$ represent ratings and characteristics of the anti-parallel, clamp diode.

*5 Pulse width and repetition rate should be such as to cause negligible temperature rise.

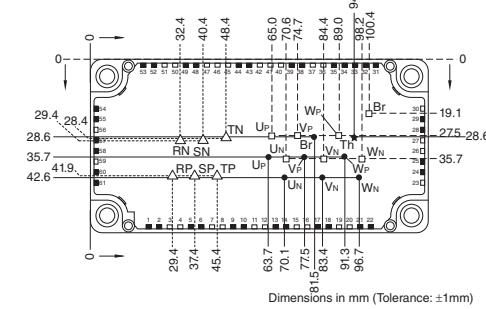
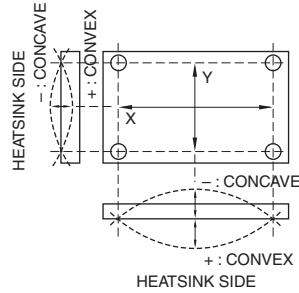
*7 Typical value is measured by using thermally conductive grease of $\lambda = 0.9$ [W/(m · K)].

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CHIP LOCATION (TOP VIEW)

□ IGBT ● FWDI △ Converter Diode ★ NTC Thermistor

BASEPLATE FLATNESS MEASUREMENT POINT





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Electrical and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Brake Sector

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector Cutoff Current	I_{CES}	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate-Emitter Threshold Voltage	$V_{GE(\text{th})}$	$I_C = 2\text{mA}$	6	7	8	Volts
Gate Leakage Current	I_{GES}	$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	μA
Collector-Emitter Saturation Voltage	$V_{CE(\text{sat})}$	$I_C = 20\text{A}, V_{GE} = 15\text{V}, T_j = 25^\circ\text{C}^5$	—	2.0	2.6	Volts
		$I_C = 20\text{A}, V_{GE} = 15\text{V}, T_j = 125^\circ\text{C}^5$	—	2.2	—	Volts
		$I_C = 20\text{A}, V_{GE} = 15\text{V}, \text{Chip}$	—	1.9	—	Volts
Input Capacitance	C_{ies}		—	—	5.1	nF
Output Capacitance	C_{oes}	$V_{CE} = 10\text{V}, V_{GE} = 0V$	—	—	0.45	nF
Reverse Transfer Capacitance	C_{res}		—	—	0.1	nF
Total Gate Charge	Q_G	$V_{CC} = 600\text{V}, I_C = 20\text{A}, V_{GE} = 15\text{V}$	—	150	—	nC
Repetitive Reverse Current	I_{RRM}^{*2}	$V_R = V_{RRM}$	—	—	1.0	mA
Forward Voltage Drop	V_{FM}^{*2}	$I_F = 20\text{A}, T_j = 25^\circ\text{C}^5$	—	2.6	3.4	Volts
		$I_F = 20\text{A}, T_j = 125^\circ\text{C}^5$	—	2.16	—	Volts
		$I_F = 20\text{A}, \text{Chip}$	—	2.5	—	Volts

Thermal and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case**	$R_{th(j-c)Q}$	Per IGBT*1	—	—	0.48	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case**	$R_{th(j-c)D}$	Per FWDI*1	—	—	1.1	$^\circ\text{C}/\text{W}$
Contact Thermal Resistance**	$R_{th(c-f)}$	Case to Heatsink (Per 1 Module) Thermal Grease Applied*1*7	—	0.015	—	$^\circ\text{C}/\text{W}$
Internal Gate Resistance	R_{Gint}	$T_C = 25^\circ\text{C}$	—	0	—	Ω
External Gate Resistance	R_G		15	—	150	Ω

Converter Sector, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Repetitive Peak Reverse Current	I_{RRM}	$V_R = V_{RRM}, T_j = 150^\circ\text{C}$	—	—	4.0	mA
Forward Voltage Drop	V_F	$I_F = 35\text{A}$	—	1.2	1.6	Volts
Thermal Resistance, Junction to Case**	$R_{th(j-c)}$	Per FWDI*1	—	—	0.45	K/W
Contact Thermal Resistance**	$R_{th(c-f)}$	Thermal Grease Applied*1*7	—	0.015	—	$^\circ\text{C}/\text{W}$

NTC Thermistor Sector, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Zero Power Resistance	R	$T_C = 25^\circ\text{C}^1$	4.85	5.00	5.15	$\text{k}\Omega$
Deviation of Resistance	$\Delta R/R$	$T_C = 100^\circ\text{C}, R_{100} = 493\Omega^1$	-7.3	—	+7.8	%
B Constant	$B(25/50)$	$B = (\ln R_1 - \ln R_2) / (1/T_1 - 1/T_2)^6$	—	3375	—	K
Power Dissipation	P_{25}	$T_C = 25^\circ\text{C}^1$	—	—	10	mW

**Thermal resistance values are per 1 element.

*1 Case temperature (T_C) and heatsink temperature (T_f) are defined on the surface of the baseplate and heatsink at just under the chip.

*2 $I_E, I_{EM}, V_{EC}, t_{rr}$ and Q_{rr} represent ratings and characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).

$I_F, I_{FM}, I_{RRM}, V_{FM}$ and V_{RRM} represent ratings and characteristics of the clamp diode.

*5 Pulse width and repetition rate should be such as to cause negligible temperature rise.

*6 R_1 : Resistance at Absolute Temperature $T_1(\text{K})$, R_2 : Resistance at Absolute Temperature $T_2(\text{K})$, $T(\text{K}) = T(\text{°C}) + 273.15$

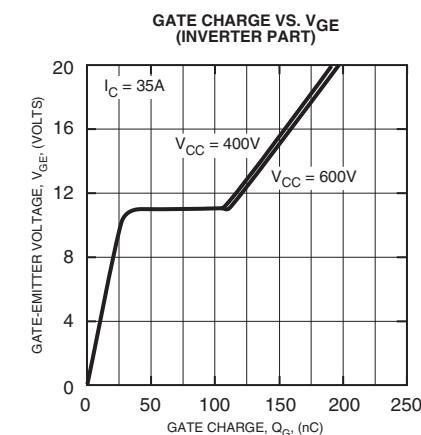
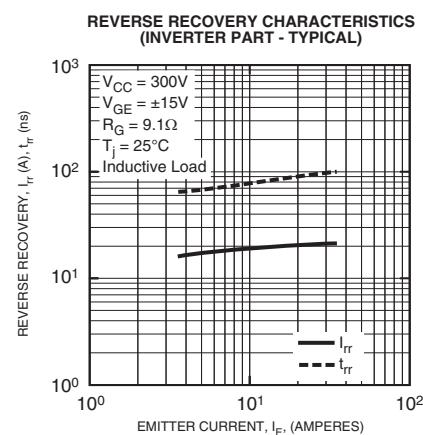
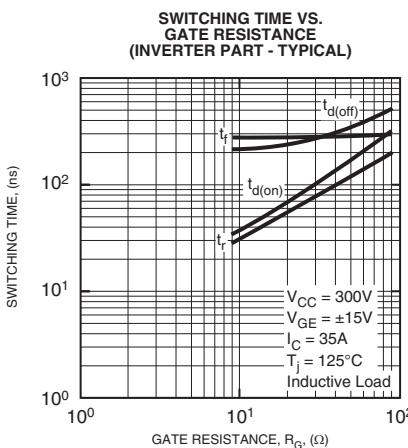
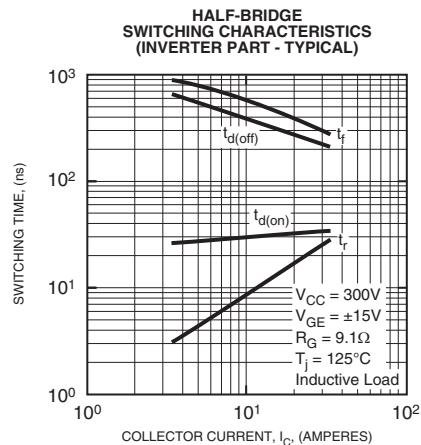
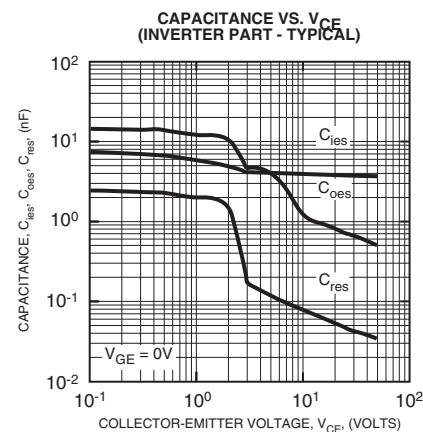
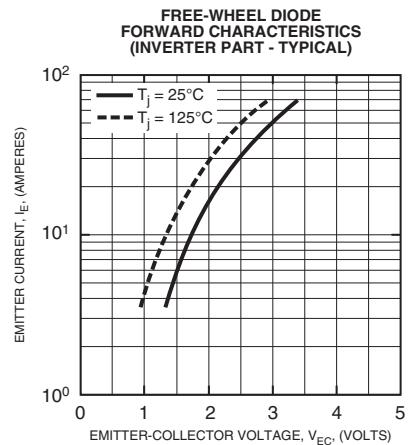
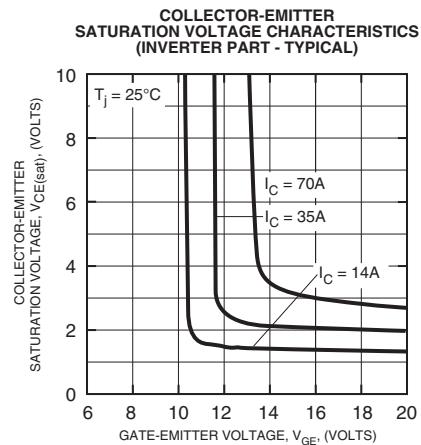
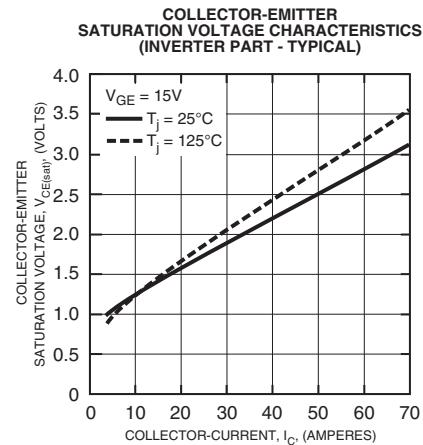
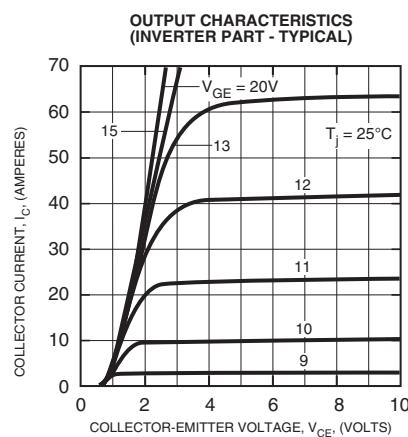
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